


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MDG/22/13163	
1.3 Title of PCI	Amkor ATP (Philippines) UQFN3X3 Chip-On-Lead (COL) package – Assembly process uniformization for STM8Sx listed products	
1.4 Product Category	STM8Sxxx (ie STM8S20x 8K)	
1.5 Issue date	2022-01-04	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	(Not Defined)	AMKOR ATP (Philippines)

4. Description of change

	Old	New
4.1 Description	Wirebond profile is Reverse Bonding. Ball on Leadfinger.	Wirebond profile is Forward Bonding. No Ball (Stitch only) on Leadfinger. (see description in additional information document).
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no change	

5. Reason / motivation for change

5.1 Motivation	To increase capacity
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Traceability of the change is ensured by ST internal tools.
------------------------	---

7. Timing / schedule

7.1 Date of qualification results	2022-03-16
7.2 Intended start of delivery	2022-04-20
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description	13163 MDG-MCD-RER2115 - 767 QFPN3x3 Chip-on-Lead Forward bonding ATP3 - reliability plan V1.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2022-01-04

9. Attachments (additional documentations)

13163 Public product.pdf
13163 MDG-MCD-RER2115 - 767 QFPN3x3 Chip-on-Lead Forward bonding ATP3 - reliability plan V1.pdf
13163 PCI13163_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM8S003F3U6TR	
	STM8S103F2U6TR	
	STM8S103F3U3TR	
	STM8S103F3U6TR	
	STM8S903F3U6TR	



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : Amkor ATP (Philippines) UQFN3X3 Chip-On-Lead (COL) package – Assembly process uniformization for STM8Sx listed products

PCI Reference : MDG/22/13163

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM8S103F3U6TR	STM8S003F3U6TR	STM8S903F3U6TR
STM8S903F3U3TR	STM8S103F2U6TR	STM8S103F3U3TR



IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.